



## Selected Papers from The Conference ISIS & ICBK 2019

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submissions:

**closed (31 August 2020)**

### Message from the Guest Editors

Dear Colleagues,

This Special Issue consists of selected excellent papers from the conference of ISIS & ICBK 2019 (**The 20th International Symposium on Advanced Intelligent Systems and 2019 International Conference on Biometrics and Kansei Engineering**), which will be held at the **International Convention Center (ICC), Jeju Island**, Korea, on 4th–7th December, 2019. In this international conference, contributors will be invited to submit and present papers to share a wide variety of ideas. The topics of the selected papers will include various sensor techniques, devices, and applications for intelligent systems. These papers will be subject to peer review and published to widely disseminate new research results, including developments and applications.

Prof. Youngchul Bae

Prof. Yongsoo Kim

*Guest Editors*





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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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